

1.7x0.6 x1.1mm Side View Chip LED

OSXX0602C1E

■Features

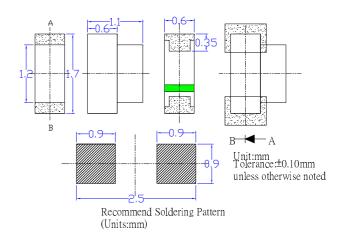
- · Single chip
- · Super high brightness of surface mount LED
- Compact package outline
 (L x W x T) of 1.7mm x 0.6mm x1.1mm
- · Compatible to IR reflow soldering.
- Water Clear Type.(Except White & Warm White)

Applications

Backlighting (switches, keys, etc.)
 Marker lights (e.g. steps, exit ways, etc.)

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■Outline Dimension



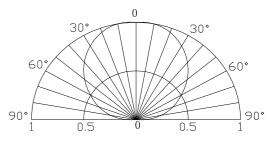
■Absolute Maximum Rating

(Ta=25°C)

Value Item Symbol Unit WA/M5/B5/G5 G8/Y5/O5/R5 DC Forward Current 30 25 mΑ Pulse Forward Current* 100 80 I_{FP} mA Reverse Voltage V_R 5 5 V Power Dissipation \mathbf{P}_{D} 102 mW $^{\circ}$ C Operating Temperature Topr -40 ~ +85 $^{\circ}$ C Storage Temperature -40~ +85 Tstg

Tsol

■Directivity



Lead Soldering Temperature

■Electrical -Optical Characteristics

(Ta=25°C)

260°C/10sec

	Color			$V_{F}(V)$			$I_R(\mu A)$	Iv(mcd)		λD(nm)		θ1/2(deg)		
Part Number				Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.
				I _F =20mA			V _R =5V	I _F =20mA						
OSWA0602C1E	White	WA		2.8	-	3.4	10	300	550	-	6000K	8500K	12500k	120
OSM50602C1E	Warm White	M5		2.8	-	3.4	10	300	400	-	2900K	3100K	3300K	120
OSB50602C1E	Blue	B5		2.8	-	3.4	10	120	250	-	460	465	475	120
OSG50602C1E	True Green	G5		2.8	-	3.4	10	350	600	-	515	523	530	120
OSG80602C1E	Yellow Green	G8		1.8	-	2.4	10	25	50	-	565	570	575	120
OSY50602C1E	Yellow	Y5		1.8	-	2.4	10	70	150	-	585	590	595	120
OSO50602C1E	Orange	O5		1.8	-	2.4	10	70	150	-	600	605	610	120
OSR50602C1E	Red	R5		1.8	-	2.4	10	70	150	-	615	620	630	120

^{*1} Tolerance of measurements of chromaticity coordinate is ±10%

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^{*}Pulse width Max 0.1ms, Duty ratio max 1/10

^{*2} Tolerance of measurements of dominant wavelength is ± 1 nm

^{*3} Tolerance of measurements of luminous intensity is $\pm 15\%$

^{*4} Tolerance of measurements of forward voltage is±0.1V



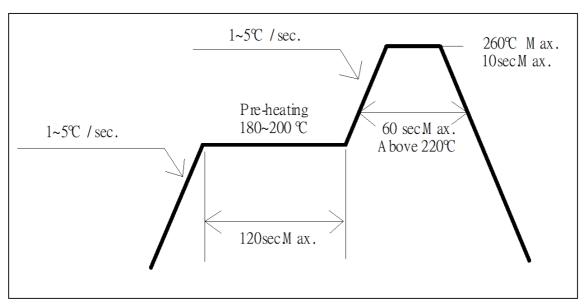
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■ Soldering Conditions

	Reflow Soldering	Hand Soldering			
Pre-Heat	180 ∼ 200°C				
Pre-Heat Time	120 sec. Max.				
Peak temperature	260°C Max.	Temperature	350°C Max.		
Dipping Time	10 sec. Max.	Soldering time	3 sec. Max.		
Condition	Refer to Temperature-profile		(one time only)		

• Reflow Soldering Condition(Lead-free Solder)



- *Recommended soldering conditions vary according to the type of LED
- *Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- *A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.







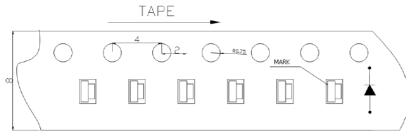




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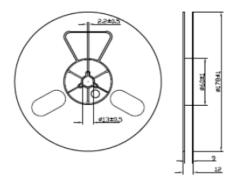
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■ PACKING



Package: 4000PCS/reel

■Reel Dimensions



Note: The tolerances unless mentioned is ±0.1mm,Unit:mm

■ Cautions:

- 1. After open the package, the LED's floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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